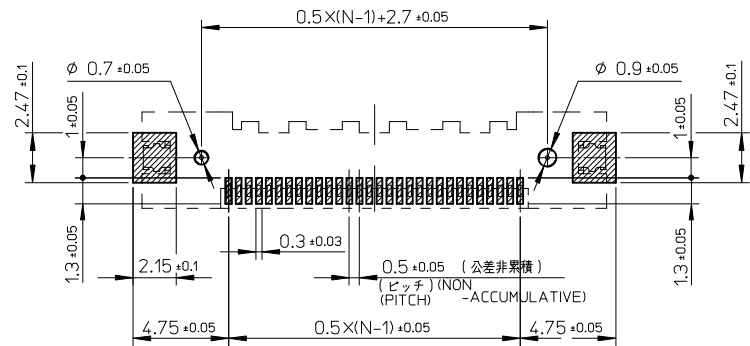
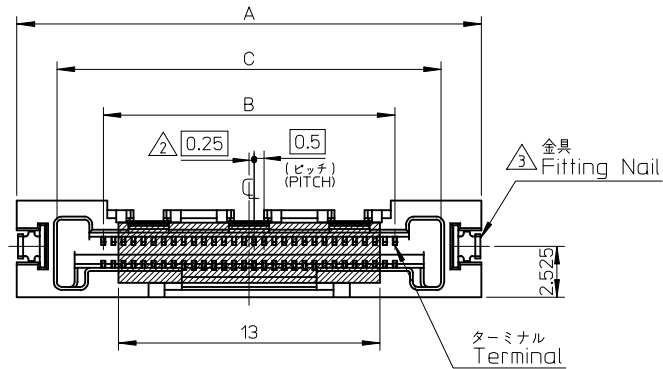
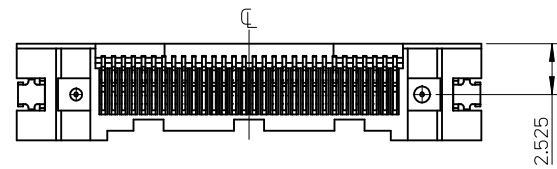
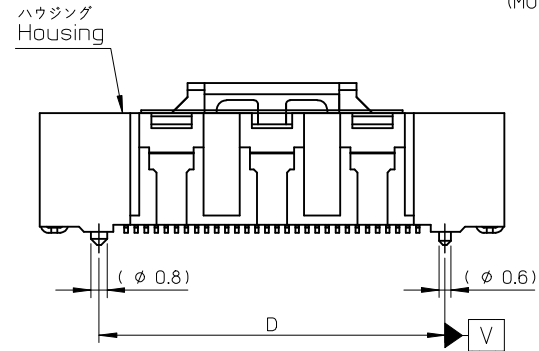
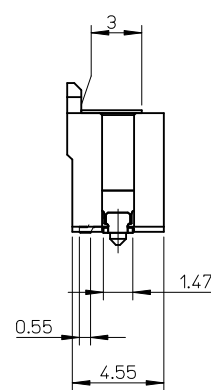
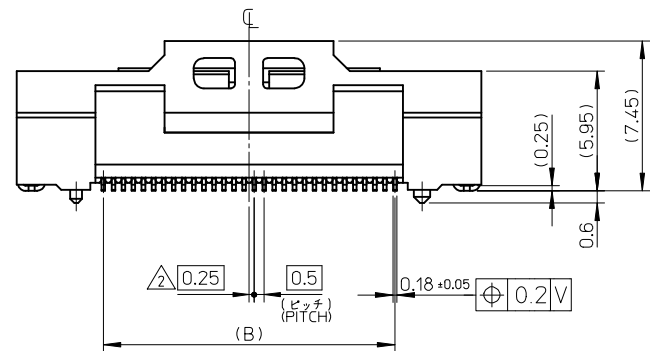


10 9 8 7 6 5 4 3 2 1



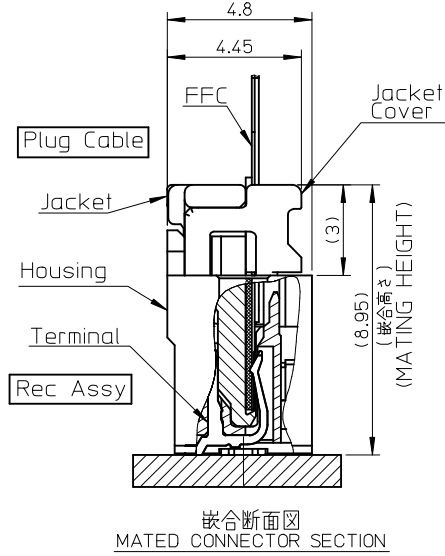
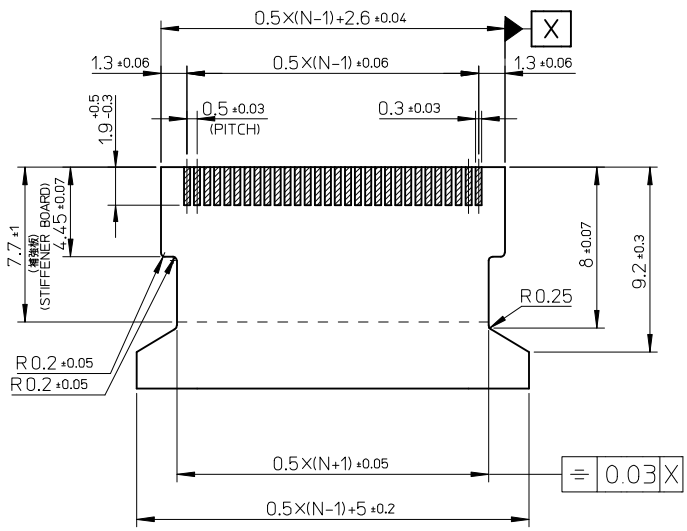
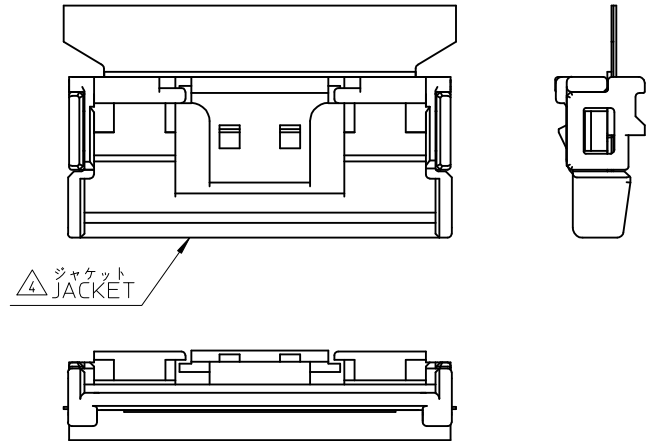
参考基板レイアウト  
P.C. BOARD PATTERN  
DIMENSION (REF.)  
(マウント面)  
(MOUNTING SIDE)



17.2	19.1	14.5	23.1	501786-3092	30
D	C	B	A	EMBOSSED TAPE PKG.	極数 CIRCUIT
ORDER No. オーダー番号					

CONNECTOR SERIES No. 501786-\*\*\*41

REVISED EC NO.: J2010-0779 DRWN: NISHI 2009/10/19 CHKD: MATSUURA 2009/10/19 APPR: MORIKAWA 2009/10/19	DESCRIPTION REV A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY H. IJIMA	DATE 07/11/26	TITLE 0.5 FFC TO BOARD CONN REC HSG ASSY(ST)				
		10 OVER 30 UNDER	± 0.25	CHECKED BY K. MORIKAWA	DATE 07/11/26	MOLEX INCORPORATED				
		30 OVER	± 0.3	APPROVED BY H. HIRATA	DATE 07/11/26	DOCUMENT NO. SD-501786-006				
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		SHEET NO. 1 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



嵌合断面図  
MATED CONNECTOR SECTION

注記  
NOTE

1. 使用材料 MATERIAL
- ハウジング HOUSING : 液晶ポリマー (LCP), ガラス充填, UL94V-0 色:黒色  
LIQUID CRYSTAL POLYMER(LCP), GLASS FILLED,UL94V-0 COLOR:BLACK
  - ターミナル TERMINAL : 銅合金 (τ=0.18)  
COPPER ALLOY(τ=0.18)
  - メッキ PLATING : ニッケル下地  
金メッキ  
CONTACT AREA OVER NICKEL PLATING  
GOLD  
ソルダーテール SOLDER TAIL : ニッケル下地  
金メッキ  
TAIL AREA OVER NICKEL PLATING  
GOLD
  - 金具 FITTING NAIL : 銅合金 (τ=0.25)  
ニッケル下地 錫メッキ  
COPPER ALLOY(τ=0.25)  
TIN OVER NICKEL PLATING.
  - グラウンド端子 GROUND TERMINAL : 銅合金 (τ=0.15)  
ニッケル下地 錫メッキ  
COPPER ALLOY(τ=0.15)  
TIN OVER NICKEL PLATING.

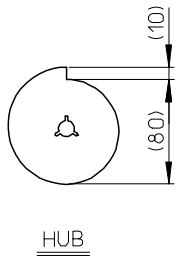
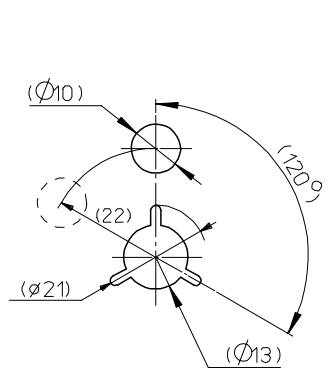
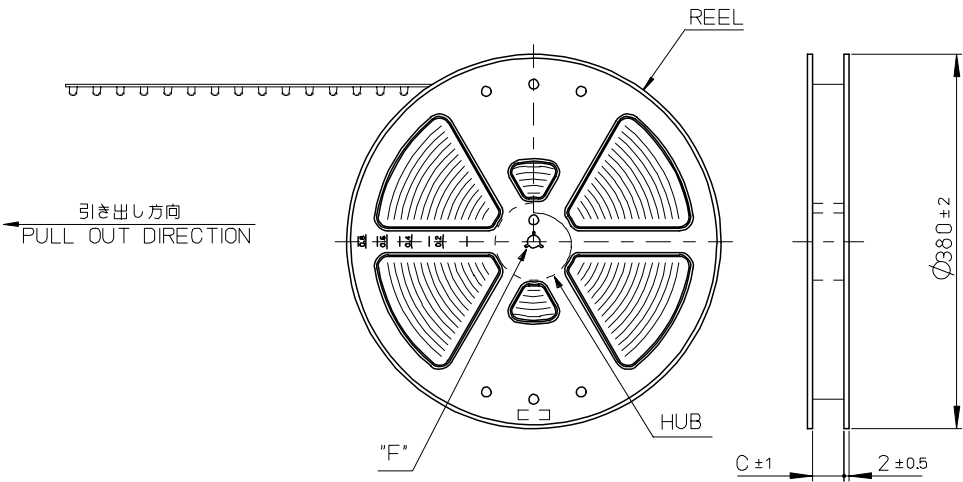
- △2 N=偶数に適用 (N:極数)  
APPLY FOR N=EVEN(CIRCUIT)
- △3 パターン剥離止め用金具  
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B PATTERN.
- △4 適合ジャケット: 501783-\*\*09  
製品詳細寸法はSD-501783-004を参照下さい。  
APPLICABLE JACKET:501783-\*\*09  
RE DETAILED DIMENSION,SEE SD-501783-004.
- △5 適合ジャケットカバー: 501784-\*\*09  
製品詳細寸法はSD-501784-004を参照下さい。  
APPLICABLE JACKET COVER:501784-\*\*09  
RE DETAILED DIMENSION,SEE SD-501784-004.

6. ELV及びRoHS適合品  
ELV AND ROHS COMPLIANT
7. FFCについて  
ABOUT FFC  
打ち抜き方向は導体側から補強板側を推奨します。  
導体部については軟箔銅35μmまたは50μmを推奨します。  
RECOMMENDED PUNCHING DIRECTION:  
FROM CONDUCTOR SIDE TO STIFFENER SIDE  
RECOMMENDED CONDUCTOR SPEC:  
SOFT COPPER FOIL  
RECOMMENDED CONDUCTOR THICKNESS:  
35MICROMETER OR 50MICROMETER

コネクタ接点部 CONTACT AREA

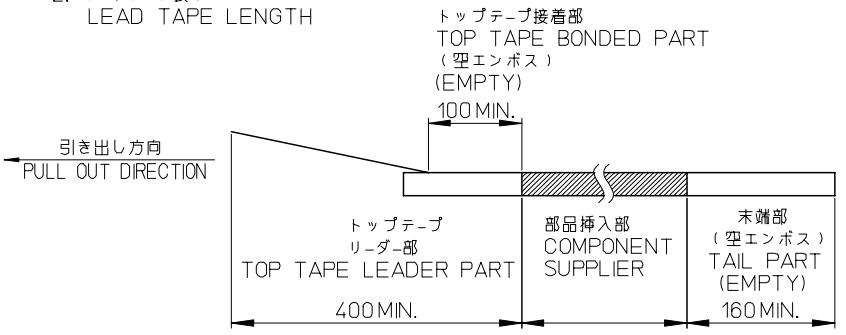
適合FFC推奨寸法  
APPLICABLE FFC  
RECOMMENDED DIMENSION  
(仕上がり厚さ:コネクタ接点部 0.3±0.03)  
(THICKNESS :CONTACT AREA 0.3±0.03)

REVISED EC NO: J2010-0779 DRMNNISHI 2009/10/19 CHKD:WATSUURA 2009/10/19 APPR:KNORIKAWA 2009/10/19	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY H.IIJIMA	DATE 07/11/26	TITLE 0.5 FFC TO BOARD CONN REC HSG ASSY(ST)	
	10 OVER 30 UNDER	±0.25	CHECKED BY K.MORIKAWA	DATE 07/11/26	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY H.HIRATA	DATE 07/11/26	DOCUMENT NO. SD-501786-006	SHEET NO. 2 OF 2
A	DESCRIPTION ANGULAR ±1° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE SHEET 1	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



NOTES

1. 梱包数量： 900 個/リール  
NUMBER OF CONNECTORS:900 PCS/REEL
2. リードテープ長さ  
LEAD TAPE LENGTH



3. 製品詳細寸法については図面 SD-501786-006を参照下さい。  
RE DETAILED DIMENSION, SEE SD-501786-006.
4. 材料(MATERIAL)  
キャリアテープ(CARRIER TAPE)：ポリスチレン(POLYSTYRENE)  
トップテープ(TOP TAPE)：PET, PE, PE  
リール(REEL)：ポリスチレン(POLYSTYRENE)<リサイクル材を含む>  
<RECYCLE MATERIAL CONTAINED>
5. ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT

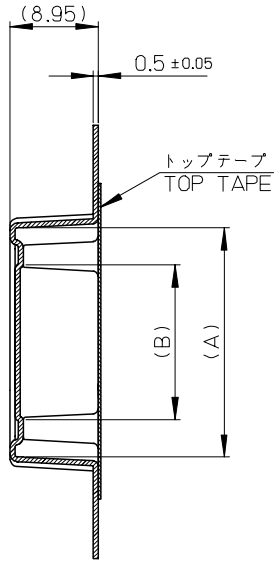
501786-\*\*92  
MODEL NO.

RELEASED EC NO: J2008-2176 DRWNG:KSETO 2007/11/29 CHKD:K MORIKAWA 2007/11/29 APPR:K MORIKAWA 2007/11/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY H. IJIMA	DATE 07/11/26	TITLE EMBSTP PKG FOR 0.5 FFC TO BOARD ST TYPE			
	10 OVER 30 UNDER	±0.25	CHECKED BY K. MORIKAWA	DATE 07/11/26	MOLEX INCORPORATED DOCUMENT NO. SD-501786-007 SHEET NO. 1 OF 2			
	30 OVER	±0.3	APPROVED BY H. HIRATA	DATE 07/11/26				
	ANGULAR	±3 °	MATERIAL NO. 501786-**92					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3						

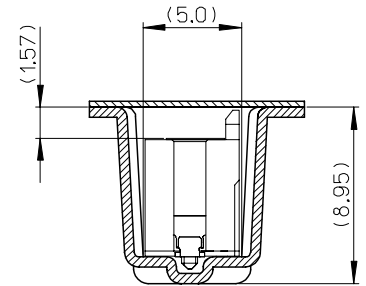
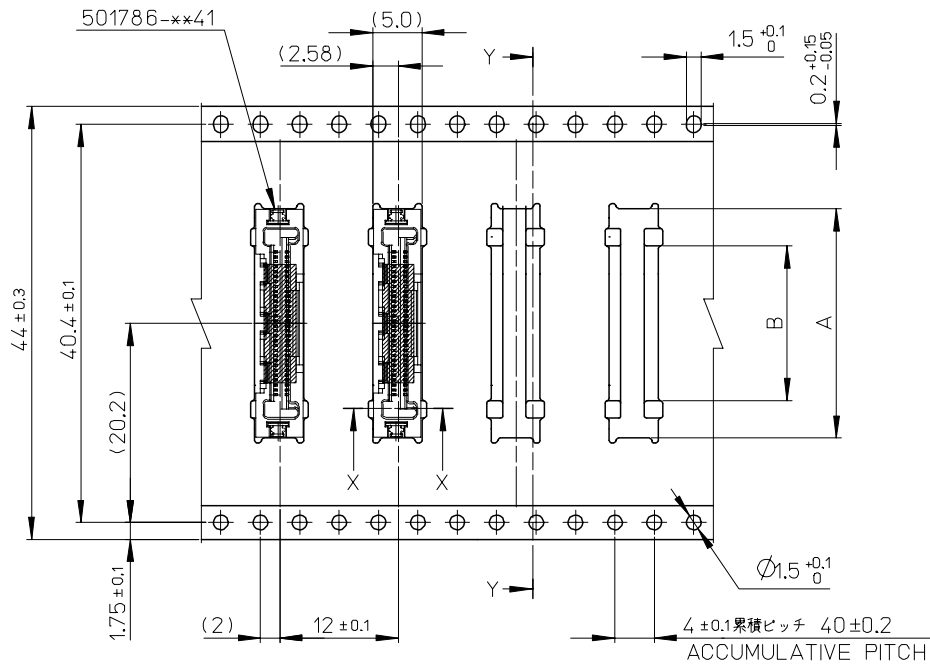
10 9 8 7 6 5 4 3 2 1

F  
E  
D  
C  
B  
A

引き出し方向  
PULL OUT DIRECTION



SECT. Y-Y



SECT. X-X

44mm幅キャリアテープ  
44mm WIDTH CARRIER TAPE

44	45.4	15.68	23.3	501786-3092	30
キャリアテープ幅 MATERIAL No.	C	B	A	製品番号 MATERIAL No.	極数 CKT

SEE SHEET 1 OF 2 EC NO: J2008-2176 DRW:KSETO 2007/11/29 CHKD:KORIKAWA 2007/11/29 APPR:KORIKAWA 2007/11/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY H. IJIMA	DATE 07/11/26	TITLE EMBSTP PKG FOR 0.5 FFC TO BOARD ST TYPE		
	10 OVER 30 UNDER	± 0.25	CHECKED BY K. MORIKAWA	DATE 07/11/26	MOLEX INCORPORATED		
	30 OVER	± 0.3	APPROVED BY H. HIRATA	DATE 07/11/26	DOCUMENT NO. SD-501786-007	SHEET NO. 2 OF 2	
0	ANGULAR	± 3 °	MATERIAL NO. 501786-**92		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							